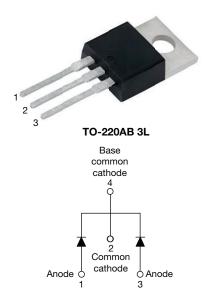
# VS-HFA30TA60C-M3

Vishay Semiconductors

### HEXFRED<sup>®</sup> Ultrafast Soft Recovery Diode, 2 x 15 A



www.vishay.com

PRIMARY CHARACTERISTICS						
I <sub>F(AV)</sub> 2 x 15 A						
V <sub>R</sub>	600 V					
V <sub>F</sub> at I <sub>F</sub>	1.2 V					
t <sub>rr</sub> typ.	19 ns					
Package	TO-220AB 3L					
Т <sub>Ј</sub> max. 150 °С						
Circuit configuration	Common cathode					

#### FEATURES

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- Designed and qualified according JEDEC®-JESD47

to

 Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

#### BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

#### DESCRIPTION

VS-HFA30TA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED<sup>®</sup> product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the t<sub>b</sub> portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Cathode to anode voltage	V <sub>R</sub>		600	V		
Maximum continuous forward currentper leg	I_	T <sub>C</sub> = 100 °C	15			
per device	IF IF	1 <sub>C</sub> = 100 C	30	۸		
Single pulse forward current	I <sub>FSM</sub>		150	A		
Maximum repetitive forward current	I <sub>FRM</sub>		60			
Maximum neuror discinction		T <sub>C</sub> = 25 °C	74	W		
Maximum power dissipation	PD	T <sub>C</sub> = 100 °C	29	vv		
Operating junction and storage temperature range	TJ, T <sub>Stg</sub>		-55 to +150	°C		

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<b>ELECTRICAL SPECIFICATIONS PER LEG</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA		600	-	-	
	I <sub>F</sub> = 15 A			-	1.3	1.7	V
Maximum forward voltage	V <sub>FM</sub>	I <sub>F</sub> = 30 A	See fig. 1	-	1.5	2.0	
		I <sub>F</sub> = 15 A, T <sub>J</sub> = 125 °C		-	1.2	1.6	
Maximum reverse	1	$V_{R} = V_{R}$ rated	See fig. 2	-	1.0	10	
leakage current	I <sub>RM</sub>	$T_J = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$	See fig. 2	-	400	1000	μA
Junction capacitance	CT	V <sub>R</sub> = 200 V	See fig. 3	-	25	50	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from p	ackage body	-	8	-	nH

<b>DYNAMIC RECOVERY CHARACTERISTICS PER LEG</b> ( $T_J = 25$ °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
<b>.</b>	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	A/μs, V <sub>R</sub> = 30 V	-	19	-		
Reverse recovery time See fig. 5 and fig. 10	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C			42	60	ns	
occ lig. o and lig. To	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	70	120		
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 15 A	-	4.0	6.0	А	
See fig. 6	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	6.5	10	~	
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C	dl <sub>F</sub> /dt = 200 A/µs V <sub>B</sub> = 200 V	-	80	180	nC	
See fig. 7	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C	v <sub>R</sub> = 200 v	-	220	600	nc	
Peak rate of fall of recovery current during t <sub>b</sub> See fig. 8	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	250	-		
	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	160	-	A/µs	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C	
Junction to case, single leg conducting	P				1.7		
Junction to case, both legs conducting	R <sub>thJC</sub>		-	-	0.85		
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	K/W	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.25	-	-	
Weight			-	6.0	-	g	
weight			-	0.21	-	oz.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style 3L TO-220AB	HFA30TA60C			•	



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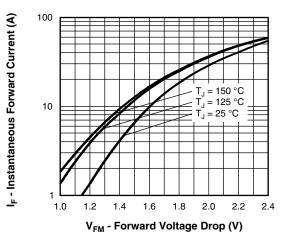


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

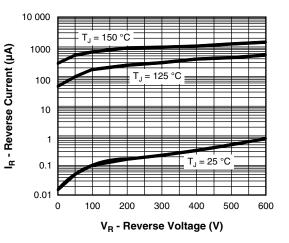


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

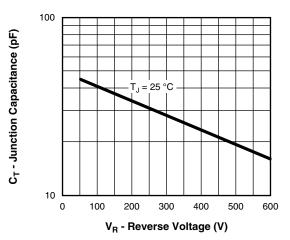


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

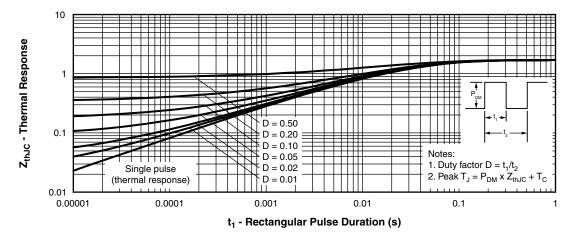


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)

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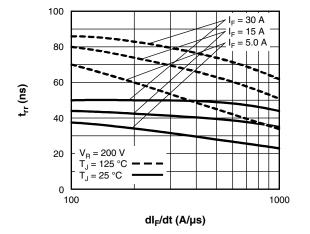


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

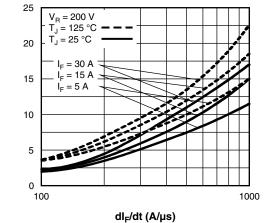
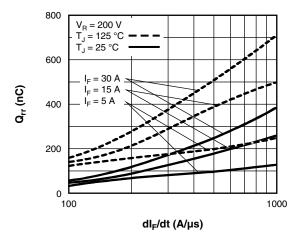


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)



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Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

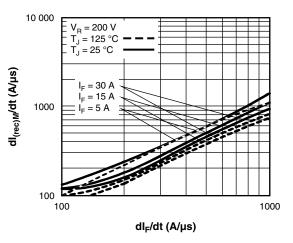


Fig. 8 - Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)

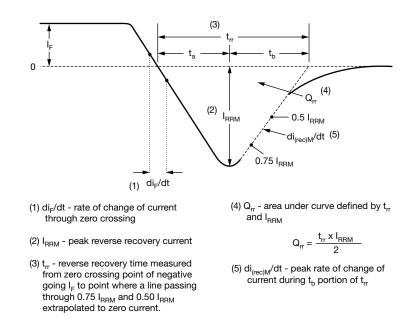


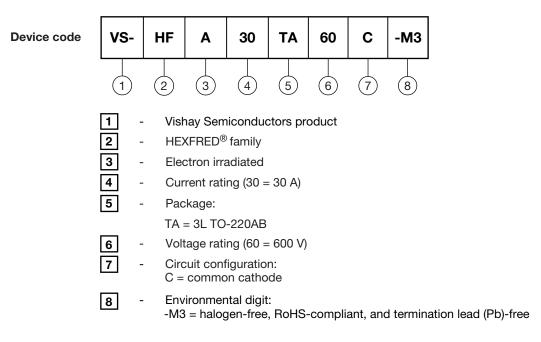
Fig. 9 - Reverse Recovery Waveform and Definitions

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#### **Vishay Semiconductors**

**ORDERING INFORMATION TABLE** 



ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-HFA30TA60C-M3	50	Antistatic plastic tube					

LINKS TO RELATED DOCUMENTS					
Dimensions www.vishay.com/doc?96154					
Part marking information	www.vishay.com/doc?95028				

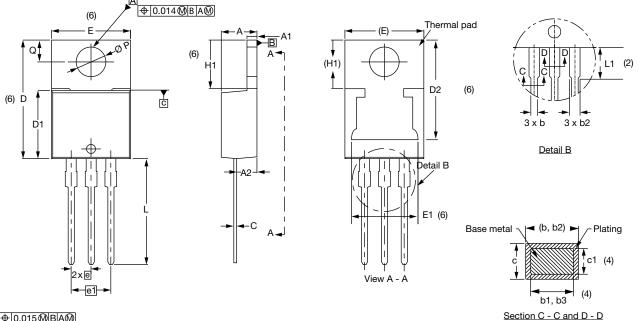




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### **TO-220AB 3L**

#### **DIMENSIONS** in millimeters and inches



⊕0.015@BA@



SYMBOL	MILLIN	IETERS	INCHES		NOTES
STINDUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.50	2.92	0.098	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.35	0.585	0.604	3
D1	8.38	9.02	0.330	0.355	

MILLIMETERS	INCHES

Conforms to JEDEC<sup>®</sup> outline TO-220AB

SYMBOL			INCILO		NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	11.68	13.30	0.460	0.524	6, 7
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØР	3.54	3.91	0.139	0.154	
Q	2.60	3.00	0.102	0.118	

Notes

 $^{(1)}\,$  Dimensioning and tolerancing as per ASME Y14.5M-1994

<sup>(2)</sup> Lead dimension and finish uncontrolled in L1

(3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

<sup>(4)</sup> Dimension b1, b3, and c1 apply to base metal only

(5) Controlling dimensions: inches

<sup>(6)</sup> Thermal pad contour optional within dimensions E, H1, D2, and E1

<sup>(7)</sup> Outline conforms to JEDEC<sup>®</sup> TO-220, except D2

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